

# Alicja Palczynska

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/8069004/publications.pdf>

Version: 2024-02-01

10  
papers

72  
citations

2258059

3  
h-index

2550090

3  
g-index

10  
all docs

10  
docs citations

10  
times ranked

26  
citing authors

| #  | ARTICLE  | IF  | CITATIONS |
|----|--|-----|-----------|
| 1  | Accuracy of CMOS-Based Piezoresistive Stress Sensor for Engineering Applications of Thermal Loading Condition: Theoretical Review and Experimental Validation. IEEE Sensors Journal, 2019, 19, 9139-9148.                                      | 4.7 | 12        |
| 2  | Towards prognostics and health monitoring: The potential of fault detection by piezoresistive silicon stress sensor. , 2016, , .   |     | 11        |
| 3  | Prognostic approaches for the wirebond failure prediction in power semiconductors: A case study using DPAK package. , 2015, , .  |     | 10        |
| 4  | <math>\text{In Situ}</math> Failure Detection of Electronic Control Units Using Piezoresistive Stress Sensor. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2018, 8, 750-763.                                       | 2.5 | 10        |
| 5  | Condition Monitoring Algorithm for Piezoresistive Silicon-Based Stress Sensor Data Obtained from Electronic Control Units. , 2017, , .   |     | 8         |
| 6  | Hybrid Approach to Conduct Failure Prognostics of Automotive Electronic Control Unit Using Stress Sensor as <math>\text{In Situ}</math> Load Counter. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 28-38. | 2.5 | 8         |
| 7  | Investigation of Uncertainty Sources of Piezoresistive Silicon Based Stress Sensor. Applied Mechanics and Materials, 0, 807, 45-54.  | 0.2 | 6         |
| 8  | In-situ investigation of EMC relaxation behavior using piezoresistive stress sensor. , 2015, , .   |     | 6         |
| 9  | Simulation Driven Design of Novel Integrated Circuits - Part 4: Method of Validation of Coupled Thermal and Thermo-mechanical Simulation. , 2018, , .  |     | 1         |
| 10 | Simulation Driven Design of Novel Integrated Circuits -- Physics of Failure Simulation of the Electronic Control Modules for Harsh Environment Application. , 2016, , .  |     | 0         |